



SLOVENSKI STANDARD

SIST EN 60352-5:2012

01-julij-2012

Nadomešča:
SIST EN 60352-5:2008

Spoji brez spajke - 5. del: Vtisnjeni spoji - Splošne zahteve, preskusne metode in praktični napotki

Solderless connections - Part 5: Press-in connections - General requirements, test methods and practical guidance

Lötfreie Verbindungen - Teil 5: Einpressverbindungen - Allgemeine Anforderungen, Prüfverfahren und Anwendungshinweise

Connexions sans soudure - Partie 5: Connexions insérées à force - Exigences générales, méthodes d'essai et guide pratique

Ta slovenski standard je istoveten z: **EN 60352-5:2012**

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EUROPEAN STANDARD
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EUROPÄISCHE NORM

EN 60352-5

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Supersedes EN 60352-5:2008

English version

**Solderless connections -
Part 5: Press-in connections -
General requirements, test methods and practical guidance
(IEC 60352-5:2012)**

Connexions sans soudure -
Partie 5: Connexions insérées à force -
Exigences générales, méthodes d'essai et
guide pratique
(CEI 60352-5:2012)

Lötfreie Verbindungen -
Teil 5: Einpressverbindungen -
Allgemeine Anforderungen, Prüfverfahren
und Anwendungshinweise
(IEC 60352-5:2012)

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CENELEC

European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

Management Centre: Avenue Marnix 17, B - 1000 Brussels

Foreword

The text of document 48B/2276/FDIS, future edition 4 of IEC 60352-5, prepared by SC 48B, "Connectors", of IEC TC 48, "Electromechanical components and mechanical structures for electronic equipment" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN 60352-5:2012.

The following dates are fixed:

- latest date by which the document has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 2012-12-28
- latest date by which the national standards conflicting with the document have to be withdrawn (dow) 2015-03-28

This document supersedes EN 60352-5:2008

EN 60352-5:2012 includes the following significant technical changes with respect to EN 60352-5:2008:

- a) Enhancement of Annex A and further application remarks are added.
- b) Editorial changes throughout the standard to prevent the document from being misunderstood as specification for establishing press-in connection in total.
- c) Deletion of all tables with hole dimensions. Historically the hole dimensions were constrained because of the dimensions of the wire wrap and clip connections posts. Since these connection technologies are no longer commonly used, the design requirements are no longer practical.
- d) Inclusion of additional figures and one table in 4.4.4 to define tolerance ranges for holes in test-boards and to illustrate them.
- e) Inclusion of a requirement for the thickness of the test-board in 4.4.

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Endorsement notice

The text of the International Standard IEC 60352-5:2012 was approved by CENELEC as a European Standard without any modification.

Annex ZA (normative)

Normative references to international publications with their corresponding European publications

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE When an international publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60050-581	2008	International Electrotechnical Vocabulary - Part 581: Electromechanical components for electronic equipment	-	-
IEC 60068-1 + corr. October + A1	1988 1988 1992	Environmental testing - Part 1: General and guidance	EN 60068-1 ¹⁾	1994
IEC 60352-1 + corr. October	1997 1998	Solderless connections - Part 1: Wrapped connections - General requirements, test methods and practical guidance	EN 60352-1	1997
IEC 60512	Series	Connectors for electronic equipment - Tests and measurements	EN 60512	Series
IEC 60512-1-100	-	Connectors for electronic equipment - Tests and measurements - Part 1-100: General - Applicable publications	EN 60512-1-100	-
IEC 61188-5-1	-	Printed boards and printed board assemblies - Design and use - Part 5-1: Attachment (land/joint) considerations - Generic requirements	EN 61188-5-1	-
IEC 61249	Series	Materials for printed boards and other interconnecting structures	EN 61249	Series
IEC 62326-4	1996	Printed boards - Part 4: Rigid multilayer printed boards with interlayer connections - Sectional specification	EN 62326-4	1997

¹⁾ EN 60068-1 includes A1 to IEC 60068-1 + corr. October.

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INTERNATIONAL STANDARD

NORME INTERNATIONALE

Solderless connections –
Part 5: Press-in connections – General requirements, test methods and practical guidance

Connexions sans soudure –
Partie 5: Connexions insérées à force – Exigences générales, méthodes d'essai et guide pratique

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CONTENTS

FOREWORD.....	4
INTRODUCTION.....	6
1 Scope and object.....	7
2 Normative references	7
3 Terms and definitions	8
4 Requirements	9
4.1 General	9
4.2 Tools	9
4.2.1 General	9
4.2.2 Tools evaluation	9
4.3 Press-in terminations.....	9
4.3.1 Materials	9
4.3.2 Dimensions of the press-in zone.....	9
4.3.3 Dimensions of the plated through hole.....	9
4.3.4 Surface finishes.....	9
4.4 Test boards	10
4.4.1 General	10
4.4.2 Materials	10
4.4.3 Thickness of test boards.....	10
4.4.4 Plated-through hole	10
4.5 Press-in connections	12
4.6 Manufacturer's specification.....	12
5 Tests	13
5.1 General remarks.....	13
5.1.1 General	13
5.1.2 Standard conditions for testing	13
5.1.3 Mounting of specimens	14
5.2 Test and measuring methods	14
5.2.1 General examination.....	14
5.2.2 Mechanical tests.....	14
5.2.3 Electrical tests	18
5.2.4 Climatic tests.....	19
5.3 Test schedules	20
5.3.1 General	20
5.3.2 Qualification test schedule.....	20
5.3.3 Flow chart	22
5.3.4 Application test schedule	22
5.4 Test report	23
5.4.1 Qualification test report	23
5.4.2 Application test report.....	24
Annex A (informative) Practical guidance.....	25
Bibliography.....	32
Figure 1 – Plated-through hole.....	10
Figure 2 – Location and example of the transversal microsection for measuring the copper thickness.....	11

Figure 3 – Example of hole ranges.....	12
Figure 4 – Test arrangement, bending	15
Figure 5 – Test arrangement – push-out force	16
Figure 6 – Transverse section of a press-in connection.....	17
Figure 7 – Longitudinal section of a press-in connection	18
Figure 8 – Test arrangement for contact resistance	19
Figure 9 – Qualification test schedule	22
Figure A.1 – Example of a termination removal tool	29
Figure A.2 – Conceptual composition of a four-layer printed circuit-board	30
Table 1 – Plated-through hole requirements for test boards	11
Table 2 – Vibration, preferred test severities.....	17
Table 3 – Qualification test schedule – Test group A.....	20
Table 4 – Qualification test schedule – Test group B.....	21
Table 5 – Qualification test schedule – Test group C	21
Table 6 – Application test schedule – Test group D.....	23
Table A.1 – Example for dimensioning the hole.....	31

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

SOLDERLESS CONNECTIONS –**Part 5: Press-in connections –
General requirements, test methods and practical guidance**

FOREWORD

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International Standard IEC 60352-5 has been prepared by subcommittee 48B: Connectors, of IEC technical committee 48: Electromechanical components and mechanical structures for electronic equipment.

This fourth edition cancels and replaces the third edition published in 2008. This edition constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

- a) Enhancement of Annex A and further application remarks are added.
- b) Editorial changes throughout the standard to prevent the document from being misunderstood as specification for establishing press-in connection in total.
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The text of this standard is based on the following documents:

FDIS	Report on voting
48B/2276/FDIS	48B/2286/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

The committee has decided that the contents of this publication will remain unchanged until the stability date indicated on the IEC web site under "<http://webstore.iec.ch>" in the data related to the specific publication. At this date, the publication will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

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INTRODUCTION

This part of IEC 60352 includes requirements, tests and practical guidance information.

Two test schedules are provided.

- a) The qualification test schedule applies to individual press-in connections (press-in zone).
They are tested to the specification provided by the manufacturer of the press-in termination (see 4.6) taking into account the requirements of Clause 4.
The qualification is independent of the application of the press-in zone in a component.
- b) The application test schedule applies to press-in connections which are part of a component and are already qualified to the qualification test schedule.
Test sequences focus on the performance of the press-in connection which is affected by the implementation in a component.

As the manufacturer of the press-in termination has to provide the main part of the information needed for qualification, the word "manufacturer" is used throughout this standard for simplicity.

IEC Guide 109 advocates the need to minimise the impact of a product on the natural environment throughout the product life cycle.

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